



LNP™ THERMOCOMP™ Compound NX10302

Asia Pacific: COMMERCIAL

This is a PC/ABS compound with improved plating, surface and mechanical performance, a good candidate for Laser Direct Structuring applications.

TYPICAL PROPERTIES ¹	TYPICAL VALUE	Unit	Standard
MECHANICAL			
Tensile Stress, yld, Type I, 5 mm/min	460	kgf/cm ²	ASTM D 638
Tensile Stress, brk, Type I, 5 mm/min	470	kgf/cm ²	ASTM D 638
Tensile Strain, yld, Type I, 5 mm/min	4.2	%	ASTM D 638
Tensile Strain, brk, Type I, 5 mm/min	100	%	ASTM D 638
Tensile Modulus, 50 mm/min	25200	kgf/cm ²	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	810	kgf/cm ²	ASTM D 790
Flexural Stress, brk, 1.3 mm/min, 50 mm span	800	kgf/cm ²	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	24400	kgf/cm ²	ASTM D 790
IMPACT			
Izod Impact, unnotched, 23°C	NB	cm-kgf/cm	ASTM D 4812
Izod Impact, notched, 23°C	61	cm-kgf/cm	ASTM D 256
THERMAL			
HDT, 1.82 MPa, 3.2mm, unannealed	108	°C	ASTM D 648
CTE, -40°C to 40°C, flow	8.47E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	9.1E-05	1/°C	ASTM E 831
PHYSICAL			
Density	1.26	g/cm ³	ASTM D 792
Water Absorption, 24 hours	0.01	%	ASTM D 570
Moisture Absorption, 50% RH, 24 hrs	0.02	%	ASTM D 570
Mold Shrinkage, flow, 24 hrs (5)	0.6 - 0.65	%	ASTM D 955
Mold Shrinkage, xflow, 24 hrs (5)	0.5 - 0.56	%	ASTM D 955
Melt Volume Rate, MVR at 260°C/5.0 kg	14	cm ³ /10 min	ISO 1133
ELECTRICAL			
Relative Permittivity, 1 GHz	2.74	-	IEC 60250
Dissipation Factor, 1 GHz	0.003	-	IEC 60250



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PROCESSING PARAMETERS	TYPICAL VALUE	Unit
Injection Molding		
Drying Temperature	85 - 100	°C
Drying Time	6 - 8	hrs
Melt Temperature	250 - 290	°C
Nozzle Temperature	250 - 290	°C
Front - Zone 3 Temperature	250 - 280	°C
Middle - Zone 2 Temperature	250 - 270	°C
Rear - Zone 1 Temperature	250 - 270	°C
Mold Temperature	60 - 90	°C
Back Pressure	0.3 - 0.7	MPa
Screw Speed	40 - 70	rpm